


**REMARKS**

Claims 42-44 are cancelled. Claim 53 is amended. Claims 60-36 are added. Claims 53-55 and 60-60 are in the application for consideration.

Examination on the merits in light of the above is requested.

Respectfully submitted,

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By:   
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. . . . . 09/783,835  
Filing Date . . . . . February 14, 2001  
Inventor . . . . . Shozo Nagano et al.  
Assignee . . . . . Honeywell International, Inc.  
Group Art Unit . . . . . Unknown  
Examiner . . . . . Unknown  
Attorney's Docket No. . . . . 30-5000-(4015)-Div3  
Title: Physical Vapor Deposition Target

**VERSION WITH MARKINGS TO SHOW CHANGES MADE  
ACCOMPANYING SUPPLEMENTAL PRELIMINARY AMENDMENT**

**In the Claims**

The claims have been amended as follows. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

Cancel claims 42-44.

53. (Amended) A physical vapor deposition target comprising an alloy of copper and one or more other elements, the one or more other elements being present in the alloy at a total concentration from less than 1.0 at% to 0.001 at% and being selected from the group consisting of ~~V, Nb, Ta, Cr, Mo, W, Mn, Tc, Re, Fe, Ru, Os, Co, Rh, Ni, Pd, Pt, Au,~~ and ~~Tl, and Pb.~~

60. (New) The physical vapor deposition target of claim 53 wherein the element comprises Mo.

61. (New) The physical vapor deposition target of claim 53 wherein the element comprises Tc.

62. (New) The physical vapor deposition target of claim 53 wherein the element comprises Re.

63. (New) The physical vapor deposition target of claim 53 wherein the element comprises Tl.

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